

**IN THE SPECIFICATION**

Please amend the specification as set forth below.

On Page 11, the paragraph beginning with "Fig. 3", please amend as follows:

Fig. 3 is a schematic sectional view showing an electronic circuit board according to the first embodiment of the present invention. This electronic circuit board is configured so that wiring conductors 34 (hereinafter collectively referring to portions 34a and 34b), resistors 35, and an insulating material (not shown) are thick-film printed and baked on the electronic circuit board 30 made of alumina. Portions 34a of the wiring conductors 34 are exposed to the air for reasons of the necessity for chip components to be soldered to the electronic circuit board 30 and for resistor trimming. The other wiring conductor portions 34b are covered with the insulating material. In this embodiment, a conductive material 1 for trapping corrosive gases is overlaid as an upper layer, by printing and baking, on a first-layer conductor 34 forming the electronic circuit wiring, with an insulating layer of a glass dielectric 33 therebetween. In the air flow sensing apparatus as shown in Fig. 4 2, corrosive gases diffusively enters from the silicone adhesive 50 used

between the metal base 10 and the resin housing 20, as described above. The gases having arrived inside the electronics apparatus, further diffuse through the silicone gel 60, which is a protective material for the electronics circuitry, or the air inside the electronics apparatus, until arriving at the electronic circuit portion.